

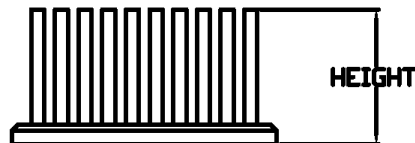
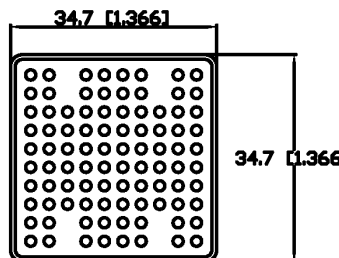
# Model : MBA35005 Series

## BGA Heat Sink Specification

For 35x35 Chip set



1. Material : CU1100
2. Dimension :  
Foot print : 35x35mm  
Height : 12, 15, 18, 21, 23, 28, 33 mm  
Base (thickness) : 2.6mm



3. Finish: Antioxidant Treatment
4. Chip set package thickness and clip color  
3.3+/-0.25mm - Yellow clip  
1.7+/-0.25mm - Blue clip  
0.8+/-0.25mm - Orange clip
5. Accessory :  
Clip : Plastic (UL94-V0)  
Thermal pad : T710 or others



## Performance

Heat Source (LxW)	15x15
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